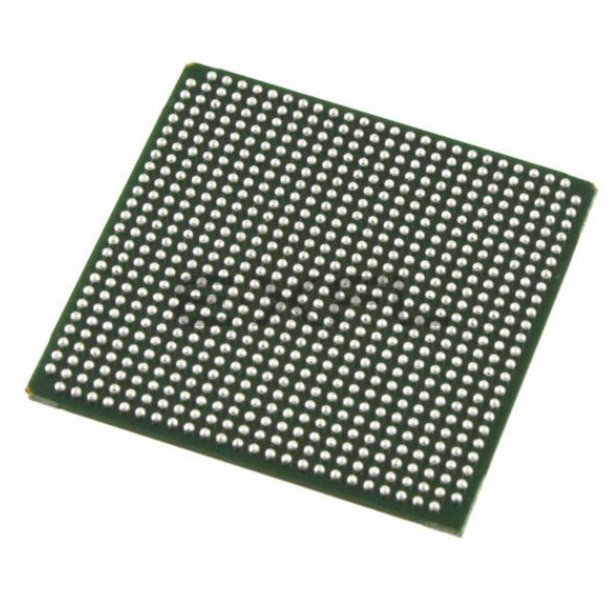

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Details	
Product Status	Obsolete
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	48000
Total RAM Bits	396288
Number of I/O	500
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-50e-6f672c

LatticeECP2/M Family Data Sheet Architecture

September 2013 **Data Sheet DS1006**

Architecture Overview

Each LatticeECP2/M device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sysDSP™ Digital Signal Processing blocks, as shown in Figure 2-1. In addition, the LatticeECP2M family contains SERDES Quads in one or more of the corners. Figure 2-2 shows the block diagram of ECP2M20 with one quad.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional Unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The LatticeECP2/M devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large dedicated 18K fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths of RAM or ROM. In addition, LatticeECP2/M devices contain up to two rows of DSP Blocks. Each DSP block has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The LatticeECP2M devices feature up to 16 embedded 3.125Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of four SERDES channels along with its Physical Coding Sub-layer (PCS) block, creates a quad. The functionality of the SERDES/PCS Quads can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every quad can be programmed by a soft IP interface, referred to as the SERDES Client Interface (SCI). These quads (up to four) are located at the corners of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the LatticeECP2/M devices are arranged in eight banks, allowing the implementation of a wide variety of I/O standards. In addition, a separate I/O bank is provided for the programming interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. The PIC logic also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as SPI4.2, along with memory interfaces including DDR2.

The LatticeECP2/M registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The LatticeECP2/M architecture provides two General PLLs (GPLL) and up to six Standard PLLs (SPLL) per device. In addition, each LatticeECP2/M family member provides two DLLs per device. The GPLLs and DLLs blocks are located in pairs at the end of the bottom-most EBR row; the DLL block is located towards the edge of the device. The SPLL blocks are located at the end of the other EBR/DSP rows.

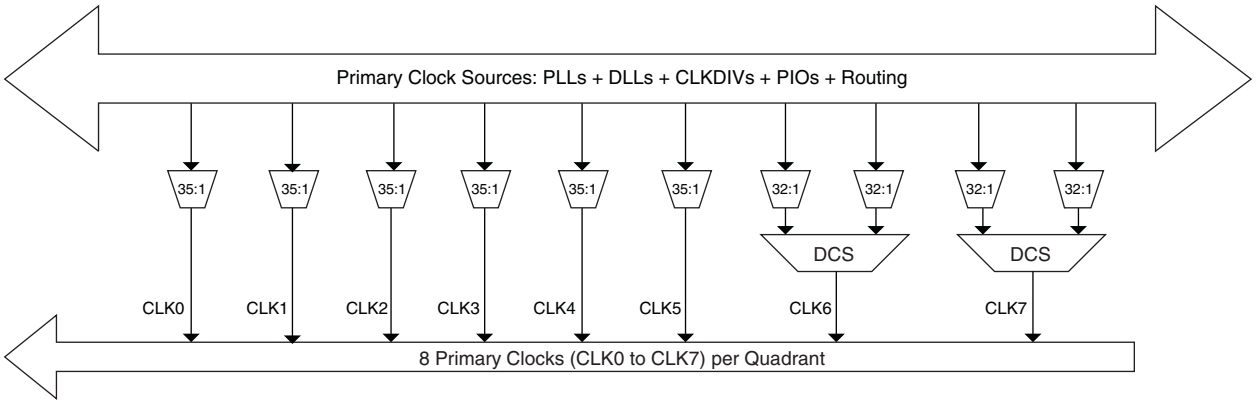
The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual boot support is located toward the center of this EBR row. The Ball Grid Array (BGA) package devices in the LatticeECP2/M family supports a sysCONFIG™ port located in the corner between banks four and five, which allows for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator. The LatticeECP2/M devices use 1.2V as their core voltage.

Primary Clock Routing

The clock routing structure in LatticeECP2/M devices consists of a network of eight primary clock lines (CLK0 through CLK7) per quadrant. The primary clocks of each quadrant are generated from muxes located in the center of the device. All the clock sources are connected to these muxes. Figure 2-13 shows the clock routing for one quadrant. Each quadrant mux is identical. If desired, any clock can be routed globally

Figure 2-13. Per Quadrant Primary Clock Selection

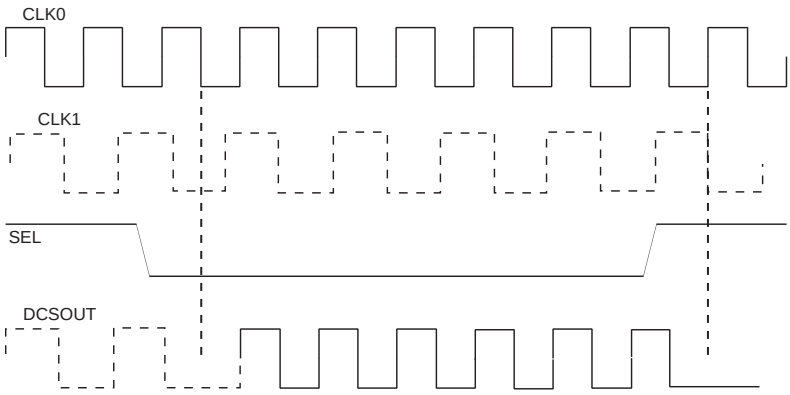


Dynamic Clock Select (DCS)

The DCS is a smart multiplexer function available in the primary clock routing. It switches between two independent input clock sources without any glitches or runt pulses. This is achieved regardless of when the select signal is toggled. There are two DCS blocks per quadrant; in total, there are eight DCS blocks per device. The inputs to the DCS block come from the center muxes. The output of the DCS is connected to primary clocks CLK6 and CLK7 (see Figure 2-13).

Figure 2-14 shows the timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information about the DCS, please see the list of additional technical documentation at the end of this data sheet.

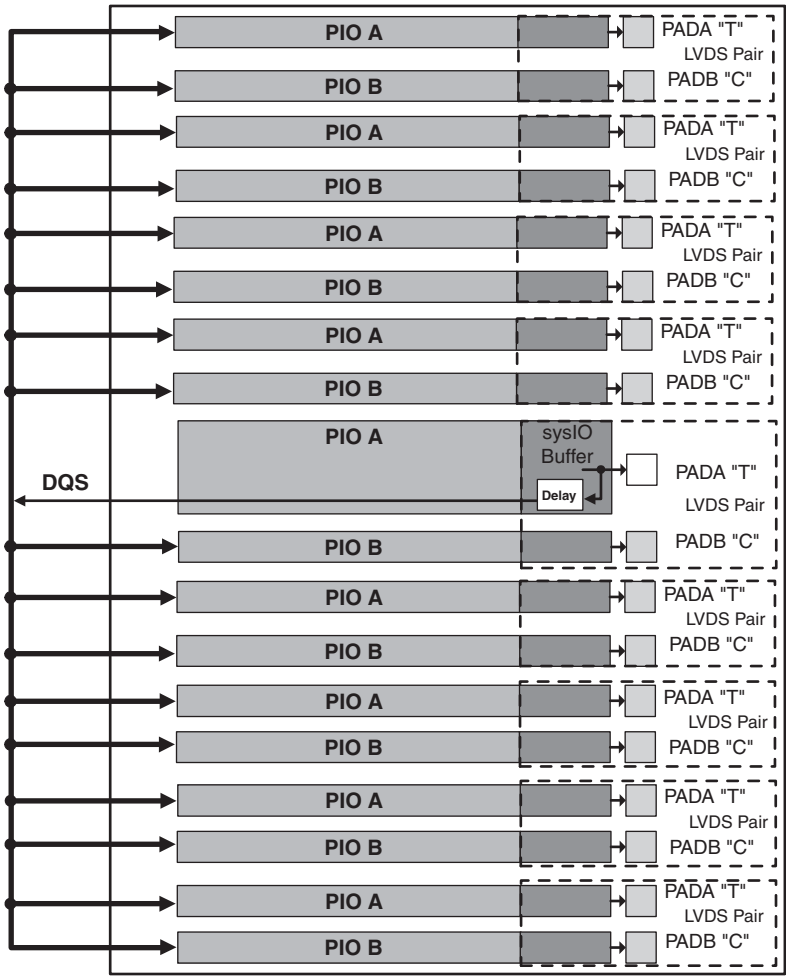
Figure 2-14. DCS Waveforms



Secondary Clock/Control Routing

Secondary clocks in the LatticeECP2 devices are region-based resources. The benefit of region-based resources is the relatively low injection delay and skew within the region, as compared to primary clocks. EBR/DSP rows and a special vertical routing channel bound the secondary clock regions. This special vertical routing channel aligns with either the left edge of the center DSP block in the DSP row or the center of the DSP row. Figure 2-15 shows

Figure 2-34. DQS Input Routing for the Bottom Edge of the Device



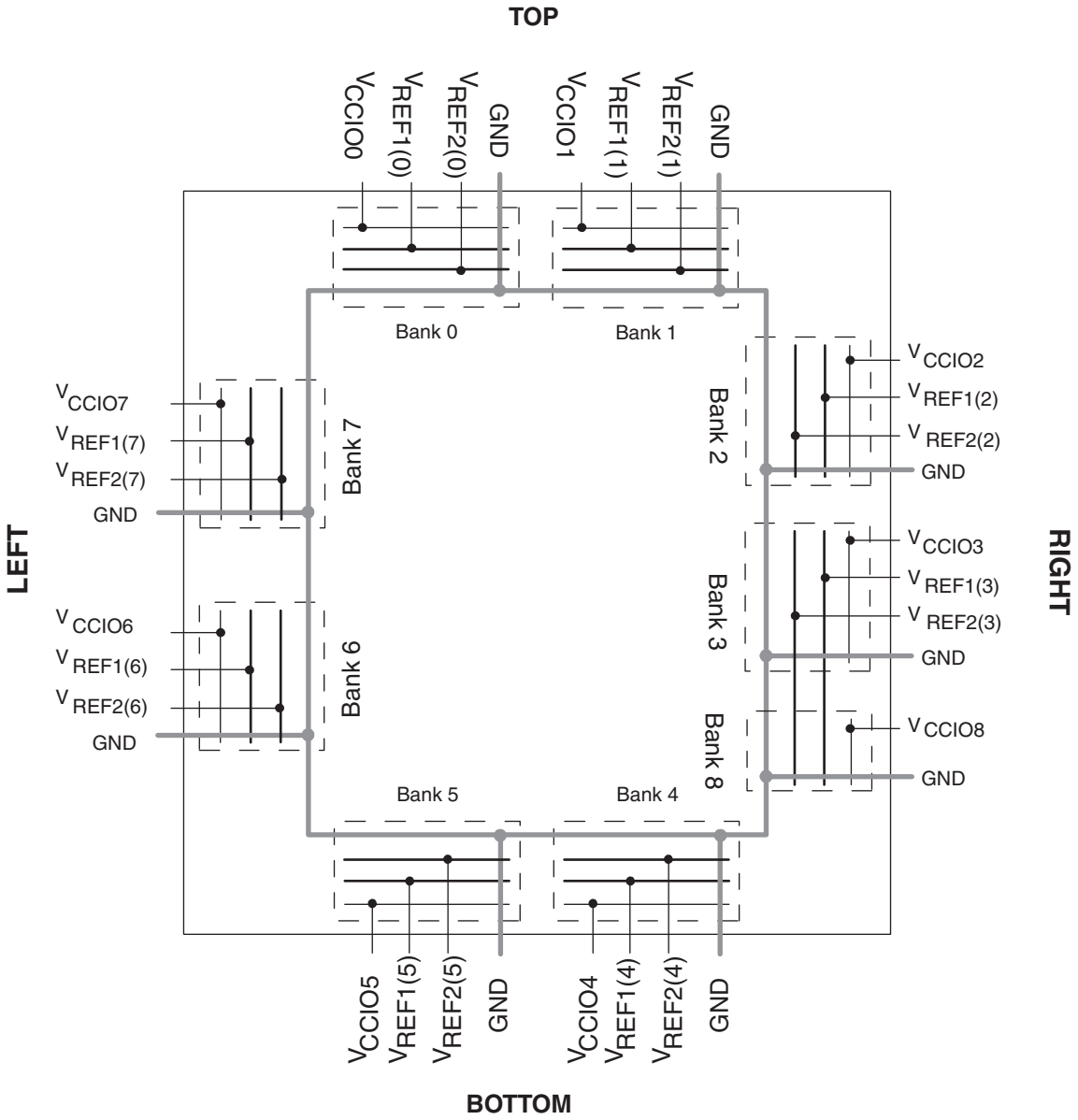
DLL Calibrated DQS Delay Block

Source synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However, in DDR memories the clock (referred to as DQS) is not free-running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only, as shown in Figure 2-35) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds polarity control logic, which controls the polarity of the clock to the sync registers in the input register blocks. Figure 2-35 and Figure 2-36 show how the DQS transition signals are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two dedicated DLLs (DDR_DLL) on opposite sides of the device. Each DLL compensates DQS delays in its half of the device as shown in Figure 2-35. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Figure 2-37. LatticeECP2 Banks



SERDES Power Supply Requirements (LatticeECP2M Family Only)[1]

Over Recommended Operating Conditions

Symbol	Description	Typ.[2]	Units
Standby (Power Down)			
$I_{CCTX-SB}$	V_{CCTX} current (per channel)	10	µA
$I_{CCRX-SB}$	V_{CCRX} current (per channel)	75	µA
$I_{CCIB-SB}$	Input buffer current (per channel)	0	µA
$I_{CCOB-SB}$	Output buffer current (per channel)	0	µA
I_{CCP-SB}	SERDES PLL current (per quad)	30	µA
$I_{CCAX33-SB}$	SERDES termination current (per quad)	10	µA
Operating (Data Rate = 3.125 Gbps)			
$I_{CCTX-OP}$	V_{CCTX} current (per channel)	19	mA
$I_{CCRX-OP}$	V_{CCRX} current (per channel)	34	mA
$I_{CCIB-OP}$	Input buffer current (per channel)	4	mA
$I_{CCOB-OP}$	Output buffer current (per channel)	13	mA
I_{CCP-OP}	SERDES PLL current (per quad)	26	mA
$I_{CCAX33-OP}$	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.
2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power[1]

Symbol	Description	Typ.[2]	Units
$P_{S-1CH-31}$	SERDES power (one channel @ 3.125 Gbps)	90	mW
$P_{S-1CH-25}$	SERDES power (one channel @ 2.5 Gbps)	87	mW
$P_{S-1CH-12}$	SERDES power (one channel @ 1.25 Gbps)	86	mW
$P_{S-1CH-02}$	SERDES power (one channel @ 250 Mbps)	76	mW

1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).
2. Typical values measured at 25ºC and 1.2V.

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35 V_{CCIO}	0.65 V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35 V_{CCIO}	0.65 V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.35 V_{CC}	0.65 V_{CC}	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3 V_{CCIO}	0.5 V_{CCIO}	3.6	0.1 V_{CCIO}	0.9 V_{CCIO}	1.5	-0.5
SSTL3 Class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 Class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 Class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
							12	-12
SSTL2 Class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
							20	-20
SSTL18 Class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
SSTL18 Class II	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.28	V_{CCIO} - 0.28	8	-8
							11	-11
HSTL Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	4	-4
							8	-8
HSTL18 Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
							12	-12
HSTL18 Class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA, where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LVPECL

The LatticeECP2/M devices support the differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

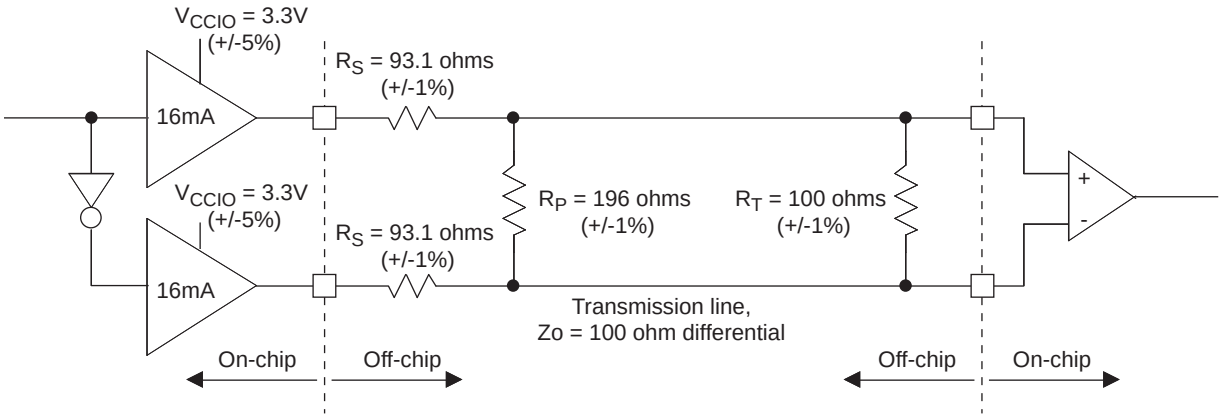


Table 3-4. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply (+/-5%)	3.30	V
Z_{OUT}	Driver Impedance	10	Ω
R_S	Driver Series Resistor (+/-1%)	93	Ω
R_P	Driver Parallel Resistor (+/-1%)	196	Ω
R_T	Receiver Termination (+/-1%)	100	Ω
V_{OH}	Output High Voltage	2.05	V
V_{OL}	Output Low Voltage	1.25	V
V_{OD}	Output Differential Voltage	0.80	V
V_{CM}	Output Common Mode Voltage	1.65	V
Z_{BACK}	Back Impedance	100.5	Ω
I_{DC}	DC Output Current	12.11	mA

1. For input buffer, see LVDS table.

LatticeECP2/M Internal Switching Characteristics[1] (Continued)

Over Recommended Operating Conditions

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{HWREN_EBR}	Hold Write/Read Enable to PFU Memory	0.139	—	0.156	—	0.173	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.123	—	0.134	—	0.145	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.081	—	-0.090	—	-0.100	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.15	—	1.26	ns
t_{SUBE_EBR}	Byte Enable Set-Up Time to EBR Output Register	-0.115	—	-0.130	—	-0.145	—	ns
t_{HBE_EBR}	Byte Enable Hold Time to EBR Output Register	0.138	—	0.155	—	0.172	—	ns
GPLL Parameters								
t_{RSTREC_GPLL}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
SPLL Parameters								
t_{RSTREC_SPLL}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
DSP Block Timing[2,3]								
t_{SUI_DSP}	Input Register Setup Time	0.12	—	0.13	—	0.14	—	ns
t_{HI_DSP}	Input Register Hold Time	0.02	—	-0.01	—	-0.03	—	ns
t_{SUP_DSP}	Pipeline Register Setup Time	2.18	—	2.42	—	2.66	—	ns
t_{tHP_DSP}	Pipeline Register Hold Time	-0.68	—	-0.77	—	-0.86	—	ns
t_{SUO_DSP}	Output Register Setup Time	4.26	—	4.71	—	5.16	—	ns
t_{HO_DSP}	Output Register Hold Time	-1.25	—	-1.40	—	-1.54	—	ns
t_{COI_DSP}	Input Register Clock to Output Time	—	3.92	—	4.30	—	4.68	ns
t_{COP_DSP}	Pipeline Register Clock to Output Time	—	1.87	—	1.98	—	2.08	ns
t_{COO_DSP}	Output Register Clock to Output Time	—	0.50	—	0.52	—	0.55	ns
$t_{SUADDSUB}$	AddSub Input Register Setup Time	-0.24	—	-0.26	—	-0.28	—	ns
$t_{HADDSUB}$	AddSub Input Register Hold Time	0.27	—	0.29	—	0.32	—	ns

1. Internal parameters are characterized but not tested on every device.
2. These parameters apply to LatticeECP devices only.
3. DSP Block is configured in Multiply Add/Sub 18x18 Mode.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP

LFE2-12E/SE					LFE2-20E/SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
1	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
2	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
3	PL4A	7		T (LVDS)*	PL6A	7	LDQ8	T (LVDS)*
4	PL4B	7		C (LVDS)*	PL6B	7	LDQ8	C (LVDS)*
5	GND	-			GND	-		
6	PL6A	7	LDQ10	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*
7	VCCAUX	-			VCCAUX	-		
8	PL6B	7	LDQ10	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*
9	PL8A	7	LDQ10	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*
10	VCCIO7	7			VCCIO7	7		
11	PL8B	7	LDQ10	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*
12	VCC	-			VCC	-		
13	GND	-			GND	-		
14	VCCIO7	7			VCCIO7	7		
15	PL12A	7	LDQ10	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*
16	PL12B	7	LDQ10	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*
17	GND	-			GND	-		
18	PL13A	7	PCLKT7_0/LDQ10	T	PL19A	7	PCLKT7_0/LDQ16	T
19	VCC	-			VCC	-		
20	PL13B	7	PCLKC7_0/LDQ10	C	PL19B	7	PCLKC7_0/LDQ16	C
21	PL15A	6	PCLKT6_0	T (LVDS)*	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*
22	PL15B	6	PCLKC6_0	C (LVDS)*	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*
23	PL16A	6	VREF2_6	T	PL22A	6	VREF2_6/LDQ25	T
24	PL16B	6	VREF1_6	C	PL22B	6	VREF1_6/LDQ25	C
25	GND	-			GND	-		
26	PL17A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*
27	PL17B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*
28	VCC	-			VCC	-		
29	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
30	VCCAUX	-			VCCAUX	-		
31	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*
32	GND	-			GND	-		
33	PL21A	6	LLM0_GPLLT_FB_A	T	PL31A	6	LLM0_GPLLT_FB_A/LDQ34	T
34	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL30B	6	LLM0_GPLLC_IN_A**/LDQ34	C (LVDS)*
35	PL21B	6	LLM0_GPLLC_FB_A	C	PL31B	6	LLM0_GPLLC_FB_A/LDQ34	C
36	PL23A	6			PL33A	6	LDQ34	
37	PL24A	6	LDQ28	T (LVDS)*	PL38A	6	LDQ42	T (LVDS)*
38	VCCIO6	6			VCCIO6	6		
39	PL24B	6	LDQ28	C (LVDS)*	PL38B	6	LDQ42	C (LVDS)*
40	VCC	-			VCC	-		
41	PL26A	6	LDQ28	T (LVDS)*	PL40A	6	LDQ42	T (LVDS)*
42	GND	-			GND	-		
43	PL26B	6	LDQ28	C (LVDS)*	PL40B	6	LDQ42	C (LVDS)*
44	VCCIO6	6			VCCIO6	6		
45	PL28A	6	LDQS28	T (LVDS)*	PL42A	6	LDQS42	T (LVDS)*

LFE2-20E/SE Logic Signal Connections: 256 fpBGA

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C3	C3	PL2A	7	VREF2_7	T (LVDS)*
C2	C2	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO	VCCIO7	7		
-	GND	GNDIO7	7		
D3	D3	PL7A	7	LDQ8	T
D4	D4	PL6A	7	LDQ8	T (LVDS)*
D2	D2	PL7B	7	LDQ8	C
GND	GND	GNDIO7	-		
E4	E4	PL6B	7	LDQ8	C (LVDS)*
B1	B1	PL13A	7	LDQ16	T
C1	C1	PL13B	7	LDQ16	C
F5	F5	PL15A	7	LDQ16	T
VCCIO	VCC	VCCIO	7		
F4	F4	PL14A	7	LDQ16	T (LVDS)*
G6	G6	PL15B	7	LDQ16	C
G4	G4	PL14B	7	LDQ16	C (LVDS)*
D1	D1	PL16A	7	LDQS16	T (LVDS)*
GND	GND	GNDIO7	-		
E1	E1	PL16B	7	LDQ16	C (LVDS)*
F3	F3	PL17A	7	LDQ16	T
G3	G3	PL17B	7	LDQ16	C
VCCIO	VCCIO	VCCIO7	7		
F2	F2	PL18A	7	LDQ16	T (LVDS)*
F1	F1	PL18B	7	LDQ16	C (LVDS)*
GND	GND	GNDIO7	-		
G2	G2	PL19A	7	PCLKT7_0/LDQ16	T
G1	G1	PL19B	7	PCLKC7_0/LDQ16	C
H6	H6	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*
VCCIO	VCCIO	VCCIO6	6		
H5	H5	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*
H4	H4	PL22A	6	VREF2_6/LDQ25	T
GND	GND	GNDIO6	-		
H3	H3	PL22B	6	VREF1_6/LDQ25	C
H2	H2	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*
H1	H1	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*
G10	G10	VCC	-		
J4	J4	PL28A	6	LLM0_GDLLT_FB_A/LDQ25	T
J5	J5	PL28B	6	LLM0_GDLLC_FB_A/LDQ25	C
J6	J6	LLM0_PLLCAP	6		
K4	K4	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*
GND	GND	GNDIO6	-		

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K12	GND	-			GND	-		
K13	GND	-			GND	-		
K15	GND	-			GND	-		
K8	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L12	GND	-			GND	-		
L13	GND	-			GND	-		
L15	GND	-			GND	-		
L8	GND	-			GND	-		
M10	GND	-			GND	-		
M11	GND	-			GND	-		
M12	GND	-			GND	-		
M13	GND	-			GND	-		
M15	GND	-			GND	-		
M8	GND	-			GND	-		
N10	GND	-			GND	-		
N11	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N15	GND	-			GND	-		
N8	GND	-			GND	-		
P14	GND	-			GND	-		
P20	GND	-			GND	-		
P3	GND	-			GND	-		
P9	GND	-			GND	-		
R10	GND	-			GND	-		
R11	GND	-			GND	-		
R12	GND	-			GND	-		
R13	GND	-			GND	-		
U17	GND	-			GND	-		
U6	GND	-			GND	-		
W2	GND	-			GND	-		
W21	GND	-			GND	-		
Y14	GND	-			GND	-		
Y9	GND	-			GND	-		
H6	NC	-			NC	-		
J6	NC	-			NC	-		
H3	NC	-			NC	-		
H2	NC	-			NC	-		
H17	NC	-			NC	-		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T24	GND	-			GND	-		
T3	GND	-			GND	-		
U10	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
V13	GND	-			GND	-		
V14	GND	-			GND	-		
V21	GND	-			GND	-		
V6	GND	-			GND	-		
M3	NC	-			NC	-		
N6	NC	-			NC	-		
P24	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-70E/SE Logic Signal Connections: 900 fpBGA

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
VCCIO	VCCIO7	7		
F4	PL2A	7	VREF2_7	T (LVDS)*
F3	PL2B	7	VREF1_7	C (LVDS)*
H4	PL3A	7		T
G5	PL3B	7		C
GND	GNDIO7	-		
D2	PL4A	7		T (LVDS)*
D1	PL4B	7		C (LVDS)*
E2	PL5A	7		T
VCCIO	VCCIO7	7		
E1	PL5B	7		C
GND	GNDIO7	-		
VCCIO	VCCIO7	7		
F1	PL14A	7	LUM1_SPLLT_IN_A/LDQ12	T (LVDS)*
F2	PL14B	7	LUM1_SPLLC_IN_A/LDQ12	C (LVDS)*
G1	PL15A	7	LUM1_SPLLT_FB_A/LDQ12	T
G2	PL15B	7	LUM1_SPLLC_FB_A/LDQ12	C
GND	GNDIO7	-		
H8	PL18A	7	LDQ21	T
H6	PL18B	7	LDQ21	C
VCCIO	VCCIO7	7		
G4	PL19A	7	LDQ21	T (LVDS)*
G3	PL19B	7	LDQ21	C (LVDS)*
H7	PL20A	7	LDQ21	T
H5	PL20B	7	LDQ21	C
GND	GNDIO7	-		
H2	PL21A	7	LDQS21	T (LVDS)*
H1	PL21B	7	LDQ21	C (LVDS)*
J6	PL22A	7	LDQ21	T
VCCIO	VCCIO7	7		
J8	PL22B	7	LDQ21	C
J2	PL23A	7	LDQ21	T (LVDS)*
J1	PL23B	7	LDQ21	C (LVDS)*
J5	PL24A	7	LDQ21	T
GND	GNDIO7	-		
J7	PL24B	7	LDQ21	C
J4	PL25A	7	LDQ29	T (LVDS)*
J3	PL25B	7	LDQ29	C (LVDS)*
K6	PL26A	7	LDQ29	T
K8	PL26B	7	LDQ29	C
VCCIO	VCCIO7	7		
K2	PL27A	7	LDQ29	T (LVDS)*

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AB6	PB17A	5	PCLKT5_0/BDQ15	T	PB35A	5	PCLKT5_0/BDQ33	T
AB7	PB17B	5	PCLKC5_0/BDQ15	C	PB35B	5	PCLKC5_0/BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
GNDIO	GNDIO5	-			GNDIO5	-		
AA8	PB22A	4	PCLKT4_0/BDQ24	T	PB40A	4	PCLKT4_0/BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
AB8	PB22B	4	PCLKC4_0/BDQ24	C	PB40B	4	PCLKC4_0/BDQ42	C
AA9	PB23A	4	VREF2_4/BDQ24	T	PB41A	4	VREF2_4/BDQ42	T
Y9	PB23B	4	VREF1_4/BDQ24	C	PB41B	4	VREF1_4/BDQ42	C
AB9	PB24A	4	BDQS24****	T	PB42A	4	BDQS42****	T
GNDIO	GNDIO4	-			GNDIO4	-		
AB10	PB24B	4	BDQ24	C	PB42B	4	BDQ42	C
AA10	PB25A	4	BDQ24	T	PB43A	4	BDQ42	T
Y11	PB25B	4	BDQ24	C	PB43B	4	BDQ42	C
VCCIO	VCCIO4	4			VCCIO4	4		
GNDIO	GNDIO4	-			GNDIO4	-		
V10	PB29A	4	BDQ33	T	PB47A	4	BDQ51	T
U11	PB29B	4	BDQ33	C	PB47B	4	BDQ51	C
V11	PB30A	4	BDQ33	T	PB48A	4	BDQ51	T
W11	PB30B	4	BDQ33	C	PB48B	4	BDQ51	C
AA11	PB31A	4	BDQ33	T	PB49A	4	BDQ51	T
AB11	PB31B	4	BDQ33	C	PB49B	4	BDQ51	C
VCCIO	VCCIO4	4			VCCIO4	4		
T11	PB32A	4	BDQ33	T	PB50A	4	BDQ51	T
U12	PB32B	4	BDQ33	C	PB50B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO4	-		
AA12	PB33A	4	BDQS33	T	PB51A	4	BDQS51	T
Y12	PB33B	4	BDQ33	C	PB51B	4	BDQ51	C
V12	PB34A	4	BDQ33	T	PB52A	4	BDQ51	T
W12	PB34B	4	BDQ33	C	PB52B	4	BDQ51	C
AB12	PB35A	4	BDQ33	T	PB53A	4	BDQ51	T
AA13	PB35B	4	BDQ33	C	PB53B	4	BDQ51	C
VCCIO	VCCIO4	4			VCCIO4	4		
T12	PB36A	4	BDQ33	T	PB54A	4	BDQ51	T
U13	PB36B	4	BDQ33	C	PB54B	4	BDQ51	C
V13	PB37A	4	BDQ33	T	PB55A	4	BDQ51	T
T13	PB37B	4	BDQ33	C	PB55B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO4	-		
AB13	PB38A	4	BDQ42	T	PB56A	4	BDQ60	T
AB14	PB38B	4	BDQ42	C	PB56B	4	BDQ60	C
U14	PB39A	4	BDQ42	T	PB57A	4	BDQ60	T
T14	PB39B	4	BDQ42	C	PB57B	4	BDQ60	C
AA14	PB40A	4	BDQ42	T	PB58A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
Y14	PB40B	4	BDQ42	C	PB58B	4	BDQ60	C
W14	PB41A	4	BDQ42	T	PB59A	4	BDQ60	T
V14	PB41B	4	BDQ42	C	PB59B	4	BDQ60	C
AB15	PB42A	4	BDQS42	T	PB60A	4	BDQS60	T

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C15	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B15	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C14	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A18	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C18	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B18	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C17	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B17	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
A16	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A17	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C16	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B14	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B13	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A14	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C13	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
-	-	-			GNDIO1	-		
-	-	-			VCCIO1	1		
E17	PT46B	1		C	PT55B	1		C
D17	PT46A	1		T	PT55A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
F17	PT45B	1		C	PT54B	1		C
D16	PT45A	1		T	PT54A	1		T
F19	PT44B	1		C	PT53B	1		C
F18	PT44A	1		T	PT53A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
E16	PT43B	1		C	PT52B	1		C
D15	PT43A	1		T	PT52A	1		T
G18	PT42B	1		C	PT51B	1		C
E15	PT42A	1		T	PT51A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
G17	PT41B	1		C	PT50B	1		C
E14	PT41A	1		T	PT50A	1		T
D14	PT40B	1		C	PT49B	1		C
D13	PT40A	1		T	PT49A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
F15	PT39B	1	VREF2_1	C	PT48B	1	VREF2_1	C
E12	PT39A	1	VREF1_1	T	PT48A	1	VREF1_1	T
H17	PT38B	1	PCLKC1_0	C	PT47B	1	PCLKC1_0	C
E13	PT38A	1	PCLKT1_0	T	PT47A	1	PCLKT1_0	T
C12	PT37B	0	PCLKC0_0	C	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G15	PT37A	0	PCLKT0_0	T	PT46A	0	PCLKT0_0	T
C11	PT36B	0	VREF2_0	C	PT45B	0	VREF2_0	C
F14	PT36A	0	VREF1_0	T	PT45A	0	VREF1_0	T

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U7	PL60A	6	VREF2_6/LDQ63	T
T8	PL60B	6	VREF1_6/LDQ63	C
R3	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6		
R2	PL61B	6	LDQ63	C (LVDS)*
R1	PL62A	6	LDQ63	T
T1	PL62B	6	LDQ63	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
T3	PL65A	6	LLM4_SPLLT_IN_A/LDQ63	T (LVDS)*
T2	PL65B	6	LLM4_SPLLC_IN_A/LDQ63	C (LVDS)*
U9	PL66A	6	LLM4_SPLLT_FB_A/LDQ63	T
U8	PL66B	6	LLM4_SPLLC_FB_A/LDQ63	C
GNDIO	GNDIO6	-		
U5	PL68A	6	LDQ72	T (LVDS)*
U4	PL68B	6	LDQ72	C (LVDS)*
V9	PL69A	6	LDQ72	T
V7	PL69B	6	LDQ72	C
VCCIO	VCCIO6	6		
U3	PL70A	6	LDQ72	T (LVDS)*
U2	PL70B	6	LDQ72	C (LVDS)*
V8	PL71A	6	LDQ72	T
U6	PL71B	6	LDQ72	C
GNDIO	GNDIO6	-		
U1	PL72A	6	LDQS72	T (LVDS)*
V2	PL72B	6	LDQ72	C (LVDS)*
V5	PL73A	6	LDQ72	T
VCCIO	VCCIO6	6		
V6	PL73B	6	LDQ72	C
V1	PL74A	6	LDQ72	T (LVDS)*
W1	PL74B	6	LDQ72	C (LVDS)*
W5	PL75A	6	LDQ72	T
GNDIO	GNDIO6	-		
W6	PL75B	6	LDQ72	C
W3	PL77A	6	LDQ81	T (LVDS)*
W4	PL77B	6	LDQ81	C (LVDS)*
W2	PL78A	6	LDQ81	T
Y4	PL78B	6	LDQ81	C
Y1	PL79A	6	LDQ81	T (LVDS)*
VCCIO	VCCIO6	6		
Y2	PL79B	6	LDQ81	C (LVDS)*
Y5	PL80A	6	LDQ81	T
Y6	PL80B	6	LDQ81	C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
C29	URC_SQ_VCCRX1	12		
B28	URC_SQ_HDINN1	12		C
C28	URC_SQ_VCCIB1	12		
A28	URC_SQ_HDINP1	12		T
B24	URC_SQ_VCCAUX33	12		
E24	URC_SQ_REFCLKN	12		C
D24	URC_SQ_REFCLKP	12		T
C24	URC_SQ_VCCP	12		
A20	URC_SQ_HDINP2	12		T
C20	URC_SQ_VCCIB2	12		
B20	URC_SQ_HDINN2	12		C
C19	URC_SQ_VCCRX2	12		
A23	URC_SQ_HDOUTP2	12		T
C23	URC_SQ_VCCOB2	12		
B23	URC_SQ_HDOUTN2	12		C
C22	URC_SQ_VCCTX2	12		
B22	URC_SQ_HDOUTN3	12		C
A21	URC_SQ_VCCOB3	12		
A22	URC_SQ_HDOUTP3	12		T
C21	URC_SQ_VCCTX3	12		
B19	URC_SQ_HDINN3	12		C
B18	URC_SQ_VCCIB3	12		
A19	URC_SQ_HDINP3	12		T
C18	URC_SQ_VCCRX3	12		
D23	PT100B	1		C
GNDIO	GNDIO1	-		
E21	PT100A	1		T
D26	PT99B	1		C
E26	PT99A	1		T
E23	PT98B	1		C
VCCIO	VCCIO1	1		
G22	PT98A	1		T
-	-	-		
D22	PT97B	1		C
F21	PT97A	1		T
G18	PT96B	1		C
H18	PT96A	1		T
D20	PT95B	1		C
GNDIO	GNDIO1	-		
D21	PT95A	1		T
E20	PT94B	1		C
VCCIO	VCCIO1	1		
E19	PT94A	1		T

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
P31	NC	-			PR39B	2		C (LVDS)*
P32	NC	-			PR39A	2		T (LVDS)*
R25	NC	-			PR38B	2		C
-	-	-			VCCIO2	2		
T24	NC	-			PR38A	2		T
N34	NC	-			PR37B	2		C (LVDS)*
N33	NC	-			PR37A	2		T (LVDS)*
GNDIO	GNDIO2	-			GNDIO2	-		
M34	PR31B	2	RDQ28	C	PR35B	2	RDQ32	C
M33	PR31A	2	RDQ28	T	PR35A	2	RDQ32	T
-	-	-			GNDIO2	-		
R24	PR30B	2	RDQ28	C (LVDS)*	PR34B	2	RDQ32	C (LVDS)*
P24	PR30A	2	RDQ28	T (LVDS)*	PR34A	2	RDQ32	T (LVDS)*
N30	PR29B	2	RDQ28	C	PR33B	2	RDQ32	C
M29	PR29A	2	RDQ28	T	PR33A	2	RDQ32	T
VCCIO	VCCIO2	2			VCCIO2	2		
N28	PR28B	2	RDQ28	C (LVDS)*	PR32B	2	RDQ32	C (LVDS)*
N29	PR28A	2	RDQS28	T (LVDS)*	PR32A	2	RDQS32	T (LVDS)*
N24	PR27B	2	RDQ28	C	PR31B	2	RDQ32	C
GNDIO	GNDIO2	-			GNDIO2	-		
N25	PR27A	2	RDQ28	T	PR31A	2	RDQ32	T
M28	PR26B	2	RDQ28	C (LVDS)*	PR30B	2	RDQ32	C (LVDS)*
M27	PR26A	2	RDQ28	T (LVDS)*	PR30A	2	RDQ32	T (LVDS)*
L27	PR25B	2	RDQ28	C	PR29B	2	RDQ32	C
VCCIO	VCCIO2	2			VCCIO2	2		
M26	PR25A	2	RDQ28	T	PR29A	2	RDQ32	T
M32	PR24B	2	RDQ28	C (LVDS)*	PR28B	2	RDQ32	C (LVDS)*
M31	PR24A	2	RDQ28	T (LVDS)*	PR28A	2	RDQ32	T (LVDS)*
GNDIO	GNDIO2	-			GNDIO2	-		
-	-	-			VCCIO2	2		
L34	PR22B	2		C	PR22B	2	RDQ23	C
L33	PR22A	2		T	PR22A	2	RDQ23	T
L32	PR21B	2		C (LVDS)*	PR21B	2	RDQ23	C (LVDS)*
L31	PR21A	2		T (LVDS)*	PR21A	2	RDQ23	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
L28	PR20B	2		C	PR20B	2	RDQ23	C
L29	PR20A	2		T	PR20A	2	RDQ23	T
M30	PR19B	2		C (LVDS)*	PR19B	2	RDQ23	C (LVDS)*
L30	PR19A	2		T (LVDS)*	PR19A	2	RDQ23	T (LVDS)*
K34	PR18B	2	RDQ15	C	PR18B	2	RDQ15	C
K33	PR18A	2	RDQ15	T	PR18A	2	RDQ15	T
GNDIO	GNDIO2	-			GNDIO2	-		
K30	PR17B	2	RDQ15	C (LVDS)*	PR17B	2	RDQ15	C (LVDS)*
K29	PR17A	2	RDQ15	T (LVDS)*	PR17A	2	RDQ15	T (LVDS)*
J34	PR16B	2	RDQ15	C	PR16B	2	RDQ15	C
J33	PR16A	2	RDQ15	T	PR16A	2	RDQ15	T
VCCIO	VCCIO2	2			VCCIO2	2		
J32	PR15B	2	RDQ15	C (LVDS)*	PR15B	2	RDQ15	C (LVDS)*
J31	PR15A	2	RDQS15	T (LVDS)*	PR15A	2	RDQS15	T (LVDS)*

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5F484C	331	1.2V	-5	fpBGA	484	COM	35
LFE2-35E-6F484C	331	1.2V	-6	fpBGA	484	COM	35
LFE2-35E-7F484C	331	1.2V	-7	fpBGA	484	COM	35
LFE2-35E-5F672C	450	1.2V	-5	fpBGA	672	COM	35
LFE2-35E-6F672C	450	1.2V	-6	fpBGA	672	COM	35
LFE2-35E-7F672C	450	1.2V	-7	fpBGA	672	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5F484C	339	1.2V	-5	fpBGA	484	COM	50
LFE2-50E-6F484C	339	1.2V	-6	fpBGA	484	COM	50
LFE2-50E-7F484C	339	1.2V	-7	fpBGA	484	COM	50
LFE2-50E-5F672C	500	1.2V	-5	fpBGA	672	COM	50
LFE2-50E-6F672C	500	1.2V	-6	fpBGA	672	COM	50
LFE2-50E-7F672C	500	1.2V	-7	fpBGA	672	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5F672C	500	1.2V	-5	fpBGA	672	COM	70
LFE2-70E-6F672C	500	1.2V	-6	fpBGA	672	COM	70
LFE2-70E-7F672C	500	1.2V	-7	fpBGA	672	COM	70
LFE2-70E-5F900C	583	1.2V	-5	fpBGA	900	COM	70
LFE2-70E-6F900C	583	1.2V	-6	fpBGA	900	COM	70
LFE2-70E-7F900C	583	1.2V	-7	fpBGA	900	COM	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5T144I	90	1.2V	-5	TQFP	144	IND	6
LFE2-6E-6T144I	90	1.2V	-6	TQFP	144	IND	6
LFE2-6E-5F256I	190	1.2V	-5	fpBGA	256	IND	6
LFE2-6E-6F256I	190	1.2V	-6	fpBGA	256	IND	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5T144I	93	1.2V	-5	TQFP	144	IND	12
LFE2-12E-6T144I	93	1.2V	-6	TQFP	144	IND	12
LFE2-12E-5Q208I	131	1.2V	-5	PQFP	208	IND	12
LFE2-12E-6Q208I	131	1.2V	-6	PQFP	208	IND	12
LFE2-12E-5F256I	193	1.2V	-5	fpBGA	256	IND	12
LFE2-12E-6F256I	193	1.2V	-6	fpBGA	256	IND	12
LFE2-12E-5F484I	297	1.2V	-5	fpBGA	484	IND	12
LFE2-12E-6F484I	297	1.2V	-6	fpBGA	484	IND	12

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.